

previously formed on the mold 10. The bonding pad 24 may be a conductive film or if not electrically conductive, a film such that the wire can be attached. In this case, the wire and bonding pad 24 integrally form the interconnecting line 20. The surface of the bonding pad 24 may be formed of the same material as the wire. For example, when the wire is of gold, the bonding pad 24 may be formed of a film of chromium, with a film of gold formed thereon.

Page 19, line 20 to page 20, line 2, delete current paragraph and insert therefor:

Then, the ends of pins 32 and 34 are disposed facing the mold 10. In more detail, the pins 32 and 34 are inserted into the hole 16 formed in the mold 10. The pin 32 is fixed to the upper die 36, and when the upper die 36 and lower die 38 are closed, the pin 32 is adapted to enter the hole 16. The pin 34 functions as a pressing-out pin when the mold is opened. The pins 32 and 34 form a through hole 44 in the molding material 40 in which the optical fiber 30 is inserted. Therefore, the pins 32 and 34 are of a shape corresponding to that of the optical fiber 30.

IN THE CLAIMS:

Please cancel claims 27 and 34 without prejudice to or disclaimer of the subject matter contained therein.

Please add new claims 35 and 36 as follows:

--35. An optical module comprising: the platform as defined in claim 22; an optical fiber inserted in the through hole; and an optical element electrically connected to the interconnecting line and mounted over the platform, wherein the optical element is provided within the indent so as to face an end surface of the optical fiber facing in the direction of the indent; and wherein a semiconductor chip which is electrically connected to the interconnecting line is further provided within the indent to face a surface of the optical element opposite to the surface facing the optical fiber.--